7. Lead in:
    a. High melting temperature type solders (i.e. lead based alloys containing more than 85 % by weight or more lead).
    b. Lead in solders for servers, storage and storage array systems, network infrastructure equipment for switching, signaling, transmission as well as network management for telecommunications.
    c. Lead in electronic ceramic parts (e.g. piezoelectronic devices).
8. Cadmium and its compounds in electrical contacts and cadmium plating except for applications banned under Directive 91/338/EC (1) amending Directive 76/769/EEC (2) relating to restrictions on the marketing and use of certain dangerous substances and preparations.
9. Lead use in compliant pin connector systems.
10. Lead as a coating material for the thermal conduction module c-ring.
11. Lead and cadmium in optical and filter glass.
12. Lead in solders consisting of more than two elements for the connection between the pins and the package of microprocessors with a lead content of more than 80% and less than 85% by weight.
13. Lead in solders to complete a viable electrical connection between semiconductor die and carrier within integrated circuit Flip Chip packages.
14. Cadmium, lead and mercury in batteries per Directive 98/101/EC not to exceed:
    a. Cadmium: 250 ppm
    b. Lead: 4,000 ppm
    c. Mercury: 5 ppm except 2% for button cells

END TABLE 1